SHENZHEN AMELIN ElECTRONICS TECHNOLOGY CO.,LTD

Specification

TFT-LCD module

Module(型号):	AML-FRD15424IPS-C
Customer (客户):	
Customer P/N (客户型号):	

If there is no special request from customer, will not reserve the tooling of the product under the following conditions:

1.There is no response from customer in one years after SHENZHEN AMELIN Electronics Technology CO.,LTD submit The samples;

2. There is no order in one years after the latest mass production. And correlated data (include quality record) will be reserved one year more after tooling was discarded.

Approved by (批准):				
Qualified(合格):	Unqualified(不合格):			

PREPARED	CHECKED	APPROVED

REVISION RECORD

REV NO	REV DATE	CONTENTS	REMARKS
1.0	2014-12-9	First Release	
2.0	2015-1-12	Second Release	

TABLE OF CONTENT

- GENERAL SPECIFICATIONS
- ABSOLUTE MAXIMUM RATINGS
- ELECTRICAL CHARACTERISTICS
- BACKLIGHT CHARACTERISTICS
- DIMENSIONAL DRAWING
- INTERFACE PIN CONNECTIONS
- ELECTRO-OPTICAL CHARACTERISTICS
- INSPECTION CRITERIA
- RELIABILITY

1.0 General Specifications

AML-FRD15424IPS-C is a color active matrix LCD module incorporating amorphous silicon TFT (Thin Film Transistor). It iscomposed of a color TFT-LCD panel, driver IC, FPC and a back light unit. The module display area contains 240x 240 pixels and can display up to 262K colors. This product accords with RoHS environmentalcriterion.

Item	Contents	Unit
LCD Type	TFT TRANSMISSIVE	/
Viewing direction	ALL DIRECTION	O' Clock
Module outline (W x HxD)	31.52*33.72*1.76	mm
Active area (WxH)	27.72*27.72	mm
Number of Dots	240(RGB) x240	/
Driver IC	ST7789V	/
Colors	262K	/
Backlight Type	LED	/
Interface Type	MCU 8 BIT	/
Input voltage	2.8	V
Appearance standard	No spot and No scratching in Active area	/

FRD15424IPS Ver: A - 3 - 240RGB240dots

2.0 ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	Vcc1,Vcc2	-0.3	4.6	v
Input voltage	Vin	0.5	VCC+ 0.5	v
Operating temperatur	Тор	-20	60	$^{\circ}$ C
Storage temperature	Tst	-30	70	$^{\circ}$ C
Humidity	RH		90%(Max60C)	RH

3.0 ELECTRICAL CHARACTERISTICS

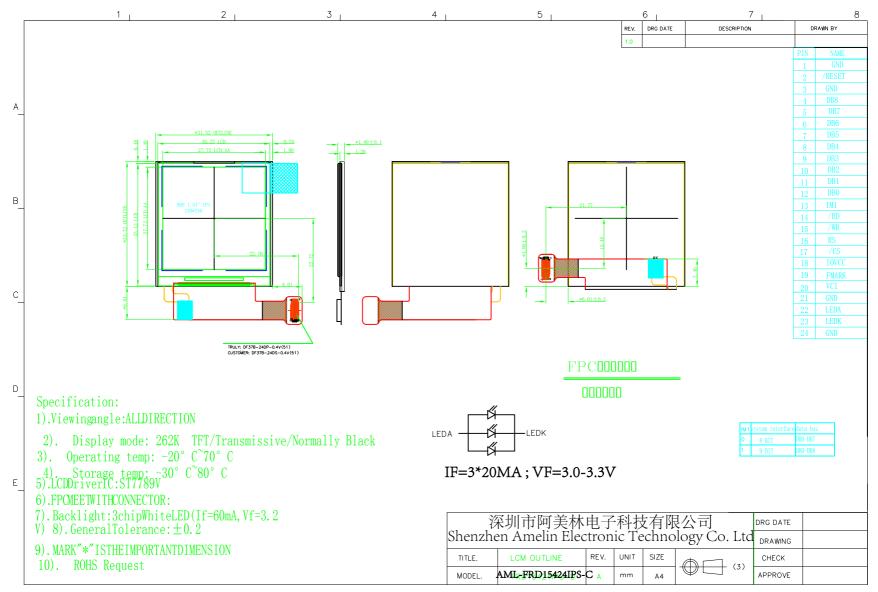
Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage for logic	Vcc -Vss	2.4	2.8	3.2	V
I/O power supply	IOVCC	1.65	1.8	3.2	V
Input Current	Idd	-	TBD	TBD	mA
Input voltage 'H'level	Vih	0.7IOVCC		IOVCC	V
Input voltage 'L'level	Vil	GND	0	0.3IOVCC	V
Output voltage ' H ' level	Voh	0.8IOVCC		IOVCC	V
Output voltage 'L'level	Vol	GND	0	0.2IOVCC	V

4.0 BACKLIGHT CHARACTERISTICS

Item	Symbol	Min	Тур	Max	Unit	Condition
Forward voltage	Vf	3.0	3.15	3.3	v	
Luminance	Lv	180	200	250	cd/m2	If=60mA
Number of LED			3		Piece	
Connection mode	S	Serial				

Using condition: constant current driving method If= 60mA(+/-10%)

5.0 DIMENSIONAL DRAWING



6.0 INTERFACE PIN CONNECTIONS

Pin.No	Symbol	Function
1	GND	Ground
2	RESET	A reset pin
3	GND	Ground
4	DB8	Data bit
5	DB7	Data bit
6	DB6	Data bit
7	DB5	Data bit
8	DB4	Data bit
9	DB3	Data bit
10	DB2	Data bit
11	DB1	Data bit
12	DB0	Data bit
13	IM1	8/9BIT system select pin
14	RD	Read data input pin
15	WR	Write data input pin
16	RS	data or command select signal input
17	CS	chip select signal input
18	IOVCC	power supply (1.8/+2.8)
19	FMARK	Tearing effect signal is used to synchronize MCU
		to frame memory writing
20	VCI	Power supply (+2.8)
21	GND	Ground
22	LEDA	Back light power supply positive
23	LEDK	back light power supply negative
24	GND	Ground

6.1 TIMING CHARACTERISTICS

6.1.1 Serial interface characteristics (4-line serial)

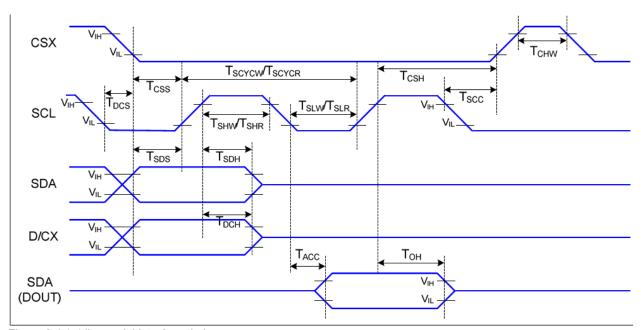


Figure 8.4.1 4-line serial interface timing

Signal	Symbol	Parameter	MIN	MAX	Unit	Description	
	TCSS Chip select setup time (write)		45		ns		
[TCSH	Chip select hold time (write)	45		ns		
CSX	TCSS	Chip select setup time (read)	60		ns		
	TSCC	Chip select hold time (read)	65		ns		
	TCHW	Chip select "H" pulse width	40		ns		
	TSCYCW	Serial clock cycle (Write)	66		ns	write command & data	
	TSHW	SCL "H" pulse width (Write)	15		ns	ram	
SCL TSLW		SCL "L" pulse width (Write)	15		ns		
I SOL	TSCYCR	Serial clock cycle (Read)	150		ns	-read command & data	
[TSHR	SCL "H" pulse width (Read)	60		ns	ram	
	TSLR	SCL "L" pulse width (Read)	60		ns	laiii	
D/CX	TDCS	D/CX setup time	10		ns		
DICX	TDCH	D/CX hold time	10		ns		
CDA	TSDS	Data setup time	10		ns		
SDA TSDH		Data hold time	10		ns	For maximum CL=30pF	
(DOUT) TA	TACC	Access time	10	50	ns	For minimum CL=8pF	
(5001)	TOH	Output disable time	15	50	ns		

Table 8.4.1 4-line Serial Interface Characteristics

6.2. Reset Input Timing

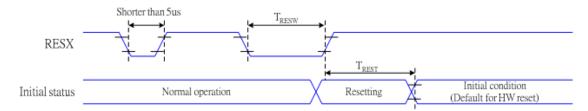


Table 9.16.1 Reset timing

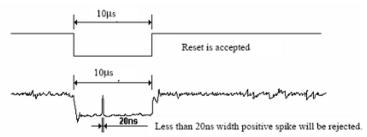
Related Pins	Symbol	Parameter	MIN	MAX	Unit
	tRESW	Reset pulse duration	10		us
RESX	tREST	Reset cancel		5	ms
	IKEST	Reset Caricel		120	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from EEPROM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

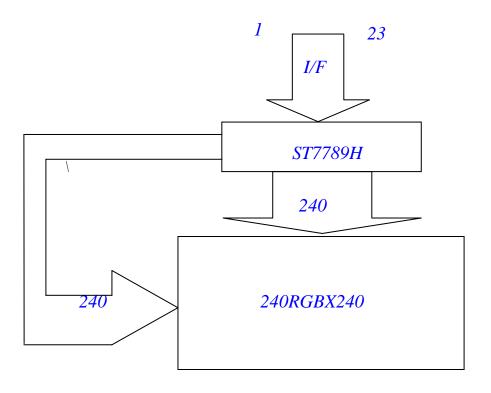
RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

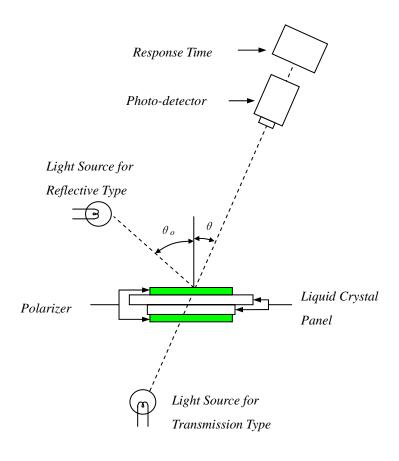
6.3 BLOCK DIAGRAM OF LCM



7. ELECTRO-OPTICAL CHARACTERISTICS

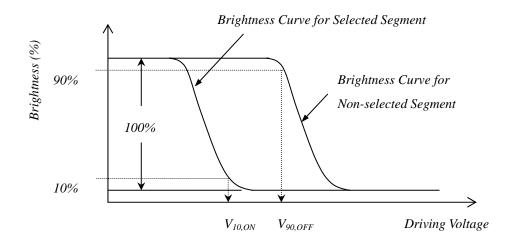
Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
Threshold Voltage		Vsat		4.1	4.3	4.5	V	Fig.1
		Vth		1.6	1.8	2.0	V	
Viewing Angle	Horizontal	Θ3	CR>10		80		0	Note 1
		Θ9			80		0	
	Vertical	Θ12			80		0	
		Θ6			80		0	
Contrast Ratio		CR	Θ= 0°		900			Note 2
Transmittance		T(%)	Θ= 0°		6.4			Note 3
NTSC		%	Θ= 0°		50			
Reproduction Of color	Red	Rx	Θ= 0°		TBD			Note 4 *CF glass
	Reu	Ry			TBD			
	Green	Gx			TBD			
		Gy			TBD			
	Plus	Bx			TBD			
	Blue	Ву			TBD			
White		Wx	Θ= 0°		TBD			
		Wy			TBD			
Response Time		Tr+Tf	Θ= 0°		35	50	ms	Note 5

7. 1 ELECTRO-OPTICAL CHARACTERISTICS TEST METHOD

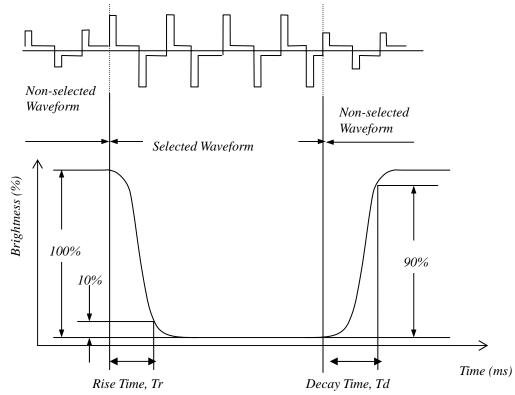


7.2 DEFINITION OF OPERATING VOLTAGE, VOP

 $Vop = (V_{10,ON} + V_{90,OFF})/2$

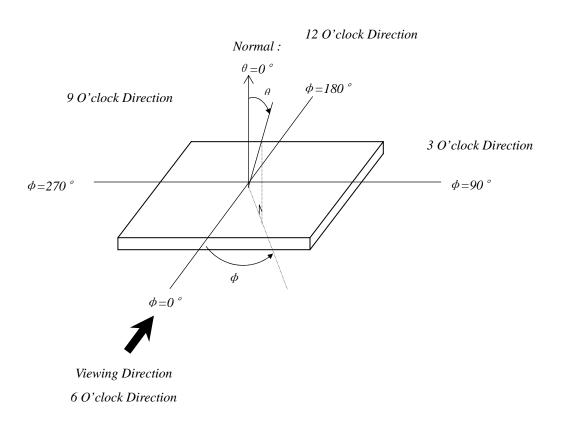


7.3 DEFINITION OF OPTICAL RESPONSE TIME



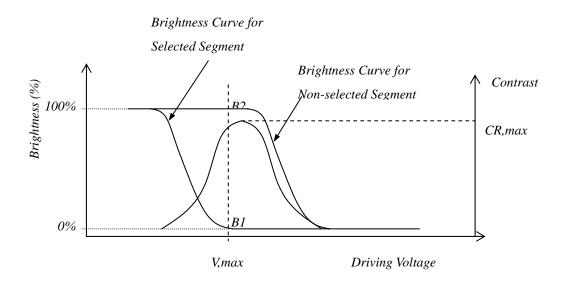
FRD15424IPS Ver: A - 12 - 240RGB240dots

7.4 DEFINITION OF VIEWING ANGLE @ AND



7.5 DEFINITION OF CONTRAST RATIO, CR

 $CR = \frac{Brightness\ of\ Non-selected\ Segment\ (B2)}{Brightness\ of\ Selected\ Segment\ (B1)}$



FRD15424IPS Ver: A - 13 - 240RGB240dots

8.INSPECTION CRITERIA

8.1 Inspection Conditions

8.1.1Environmental conditions

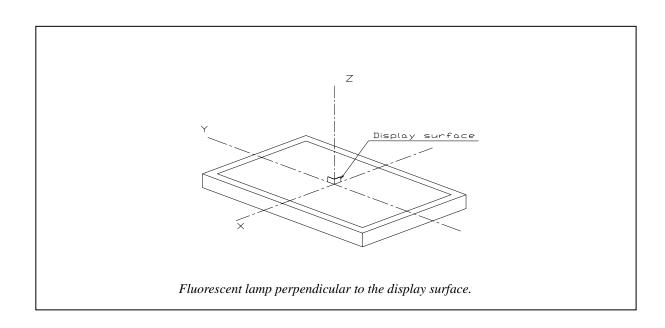
The environmental conditions for inspection shall be as follows

Room temperature: 20±3°C Humidity: 65±20%RH

8.1.2 The external visual inspection

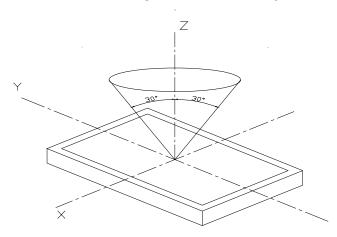
With a single 20-watt fluorescent lamp as the light source, the inspection was in the distance of 30cm or more from the LCD to the inspector's eyes.

8.2 LIGHT METHOD



FRD15424IPS Ver: A - 14 - 240RGB240dots

Inspection distance and angle



Inspection should be performed within angle $\phi(\phi)$ is usually 30°) from Z axis to each X and Y. Inspection distance in any direction within ϕ must be kept 30±5cm from the display surface.

8.3 Classification of defects

9.3.1Major defect

A major defect refers to a defect that may substantially degrade usability for product applications.

9.3.2 Minor defect

A minor defect refers to a defect which is not considered to be able substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation.

FRD15424IPS Ver: A - 15 - 240RGB240dots

9. RELIABILITY

9.1 MTBF

The LCD module shall be designed to meet a minimum MTBF value of 50000 hours with normal. (25°C in the room without sunlight)

9.2 **TESTS**

NO.	Test Item	Test condition	Criterion
1	High Temperature Storage	80℃±2℃ 96H Restore 2H at 25℃ Power off	
2	Low Temperature Storage	-30°C±2°C 96H Restore 2H at 25°C Power off	
3	High Temperature Operation	70°C±2°C 96H Restore 2H at 25°C Power on	
4	Low Temperature Operation	-20°C±2°C 96H Restore 4H at 25°C Power on	
5	High Temperature & Humidity Operation	60°C±2°C 90%RH 96H Power on	
6	Temperature Cycle	30°C ←→25°C ←→80°C 30min 5min 30min after 10cycle, Restore 2H at 25 °C Power off	Aftertesting,cosmetic and electrical defects should not happen.
7	Vibration Test	10Hz~150Hz, 100m/s2, 120min	
8	Shock Test	Half-sinewave,300m/s2,11ms	
9	Drop Test(package state)	800mm, concrete floor,1corner, 3edges, 6 sides each time	1.After testing, cosmetic and electrical defects should not happen. 2.the product should remain at initial place 3.Product uncovered or package broken is not permitted.

FRD15424IPS Ver: A - 16 - 240RGB240dots